

1200V/450A 2 in one-package

Preliminary Data

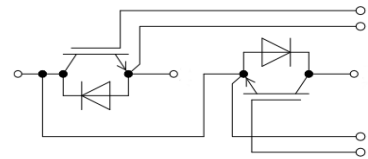
Features:

- 1200V/450A, $V_{CE(sat)(typ)}=2.60V$
- SPT (Soft Punch Through) technology
- Lower losses
- Higher system efficiency
- Excellent short-circuit capability
- Square RBSOA



General Applications:

Daxin's IGBTs offer ultrafast switching speed for application such as welding, inductive heating, UPS and other high frequency applications



Equivalent Circuit Schematic

Absolute Maximum Ratings of IGBT

V_{CES}	Collector to Emitter Voltage		1200	V
V_{GES}	Continuous Gate to Emitter Voltage		± 30	V
I_C	Continuous Collector Current	$T_C = 25^\circ C$	900	A
		$T_C = 100^\circ C$	450	
I_{CM}	Pulse Collector Current	$T_J = 150^\circ C$	900	A
P_D	Maximum Power Dissipation (IGBT)	$T_C = 25^\circ C, T_J = 150^\circ C$	1360	W
t_{sc}	Short Circuit Withstand Time		> 10	μs
T_J	Maximum IGBT Junction Temperature		150	$^\circ C$
T_{JOP}	Maximum Operating Junction Temperature Range		-40 to +150	$^\circ C$
T_{stg}	Storage Temperature Range		-40 to +125	$^\circ C$

Absolute Maximum Ratings of Freewheeling Diode

V_{RRM}	Repetitive Peak Reverse Voltage	Preliminary Data	1200	V
I_F	Diode Continuous Forward Current	$T_C = 25^\circ C$	900	A
		$T_C = 100^\circ C$	450	
I_{FM}	Diode Maximum Forward Current		900	A

Electrical Characteristics of IGBT at T_J = 25°C (Unless Otherwise Specified)

Parameter		Test Conditions	Min	Typ	Max	Unit	
BV _{CES}	Collector to Emitter Breakdown Voltage	V _{GE} = 0V, I _C = 1mA	1200			V	
I _{CES}	Collector to Emitter Leakage Current	V _{GE} = 0V, V _{CE} = V _{CES}			5	mA	
I _{GES}	Gate to Emitter Leakage Current	V _{GE} = ±30V, V _{CE} = 0V			400	nA	
V _{GE(th)}	Gate Threshold Voltage	I _C = 2mA, V _{CE} = V _{GE}	4.5		5.7	V	
V _{CE(sat)}	Collector to Emitter Saturation Voltage (Module Level)	I _C = 450A, V _{GE} = 15V	T _J = 25°C		2.60	2.80	V
			T _J = 125°C		3.00		

Switching Characteristics of IGBT

t _{d(on)}	Turn-on Delay Time	V _{CC} = 900V I _C = 450A R _G = 1.1Ω V _{GE} = ±15V Inductive Load	T _J = 25°C		65		ns
			T _J = 125°C		70		
t _r	Turn-on Rise Time		T _J = 25°C		110		ns
			T _J = 125°C		120		
t _{d(off)}	Turn-off Delay Time		T _J = 25°C		520		ns
			T _J = 125°C		580		
t _f	Turn-off Fall Time		T _J = 25°C		100		ns
			T _J = 125°C		130		
E _{on}	Turn-on Switching Loss		T _J = 25°C		20.5		mJ
			T _J = 125°C		31.0		
E _{off}	Turn-off Switching Loss	T _J = 25°C		35.0		mJ	
		T _J = 125°C		52.0			
Q _g	Total Gate Charge	T _J = 25°C		4560		nC	
R _{gint}	Integrated gate resistor	f = 1M; V _{pp} = 1V	T _J = 25°C		2.5		Ω
C _{ies}	Input Capacitance	V _{CE} = 25V V _{GE} = 0V f = 1MHz	T _J = 25°C		21.5		nF
C _{oes}	Output Capacitance		T _J = 25°C		3.30		
C _{res}	Reverse Transfer Capacitance		T _J = 25°C		1.90		
R _{θJC}	Thermal Resistance, Junction-to-Case (IGBT)				0.092		°C/W

Electrical and Switching Characteristics of Freewheeling Diode

V _F	Diode Forward Voltage	I _F = 450A , V _{GE} = 0V	T _J = 25°C	1.90	2.20	V
			T _J = 125°C	1.90		
t _{rr}	Diode Reverse Recovery Time	I _F = 450A, di/dt=8500A/μs, V _{rr} = 600V,	T _J = 25°C	230		ns
			T _J = 125°C	400		
I _{rr}	Diode Peak Reverse Recovery Current	I _F = 450A, di/dt=8500A/μs, V _{rr} = 600V,	T _J = 25°C	450		A
			T _J = 125°C	760		
Q _{rr}	Diode Reverse Recovery Charge	I _F = 450A, di/dt=8500A/μs, V _{rr} = 600V,	T _J = 25°C	58.0		μC
			T _J = 125°C	85.0		
E _{rr}	Diode Reverse Recovery Energy	I _F = 450A, di/dt=8500A/μs, V _{rr} = 600V,	T _J = 25°C	18.0		mJ
			T _J = 125°C	29.5		
R _{θJC}	Thermal Resistance, Junction-to-Case (Diode)				0.095	°C/W

Module Characteristics

Parameter		Min.	Typ.	Max.	Unit
V _{iso}	Isolation Voltage (All Terminals Shorted), f = 50Hz, 1minute	2500			V
R _{θCS}	Case-To-Sink(Conductive Grease Applied)		0.1		°C/W
M	Power Terminals Screw: M6	3.0		5.0	N·m
M	Mounting Screw: M6	4.0		6.0	N·m
G	Weight		315		g

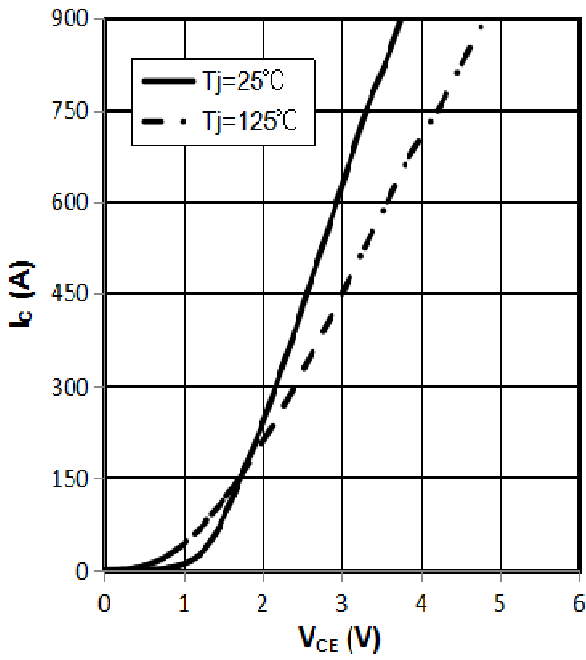


Fig 1. output characteristic IGBT,
 $I_c=f(V_{CE}), V_{GE}=15V$

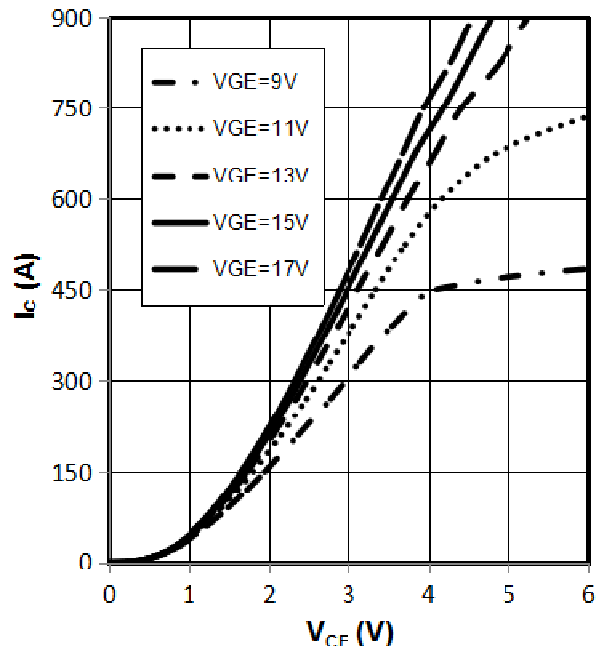


Fig 2. output characteristic IGBT,
 $I_c=f(V_{CE}), T_j=125^\circ C$

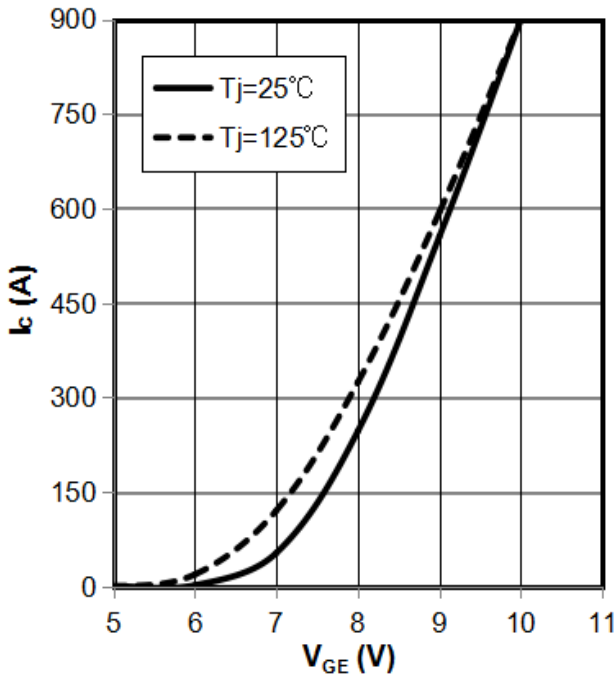


Fig 3. transfer characteristic IGBT,
 $I_c=f(V_{GE}), V_{CE}=20V$

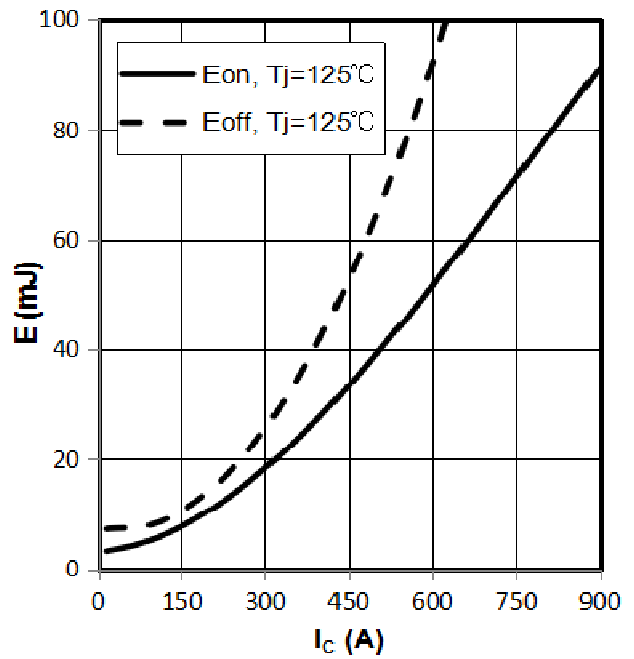


Fig 4. switching losses IGBT, $E_{on}=f(I_c), E_{off}=f(I_c)$,
 $V_{GE}=\pm 15V, R_{Gon}=1.1\Omega, R_{Goff}=1.1\Omega, V_{CE}=600V$

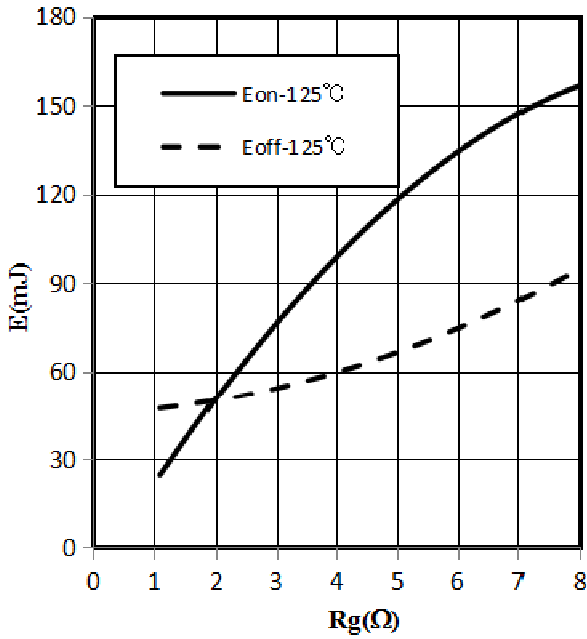


Fig 5. switching losses IGBT, $E_{on}=f(R_g), E_{off}=f(R_g)$, $V_{GE}=\pm 15\text{V}, I_c=300\text{A}, V_{CE}=600\text{V}$

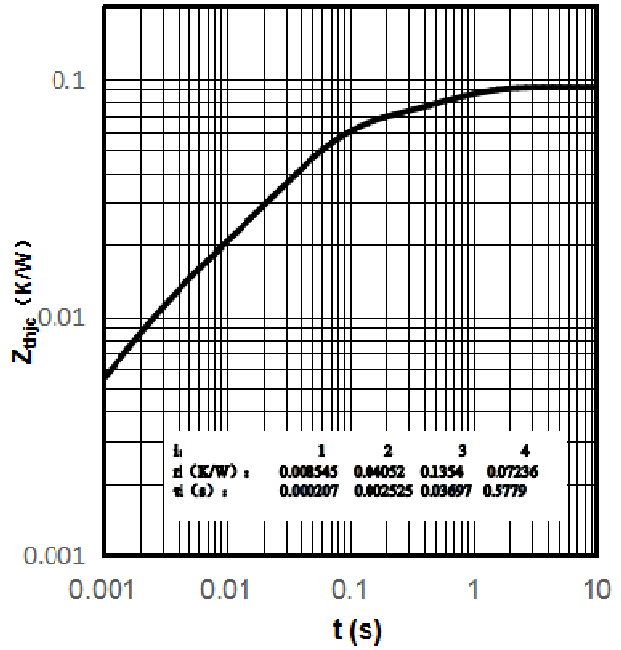


Fig 6. transient thermal impedance IGBT, $Z_{thjc}=f(t)$

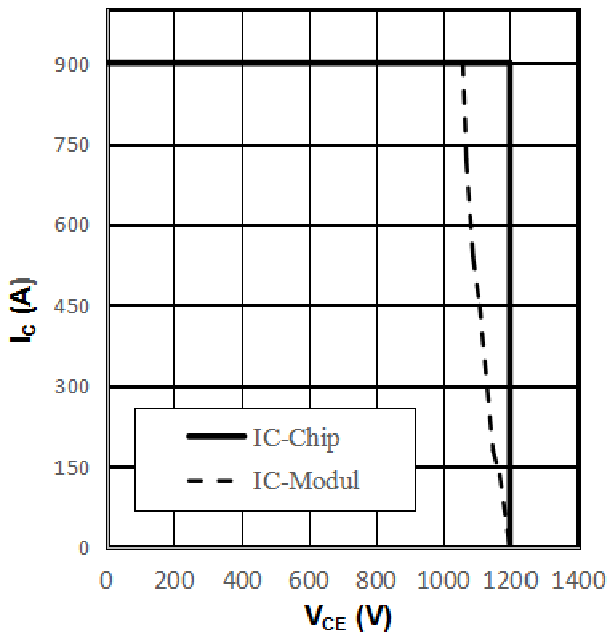


Fig 7. reverse bias safe operating area IGBT, $I_c=f(V_{CE}), V_{GE}=\pm 15\text{V}, R_{Goff}=3.3\Omega, T_{vj}=125^\circ\text{C}$

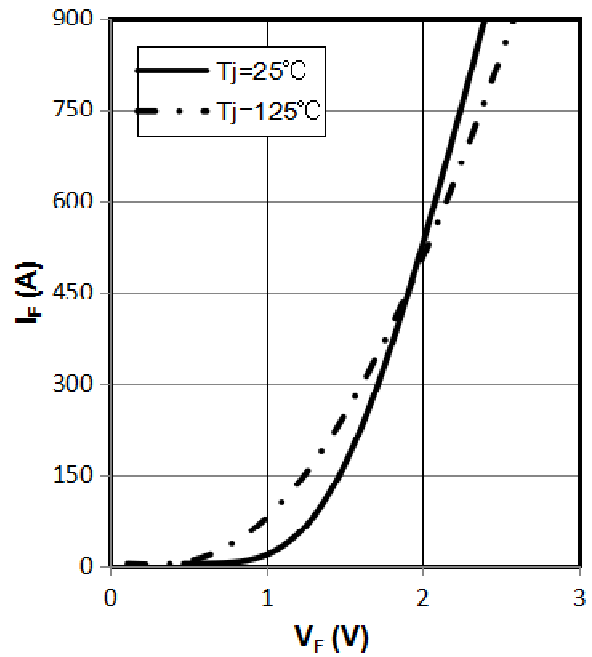
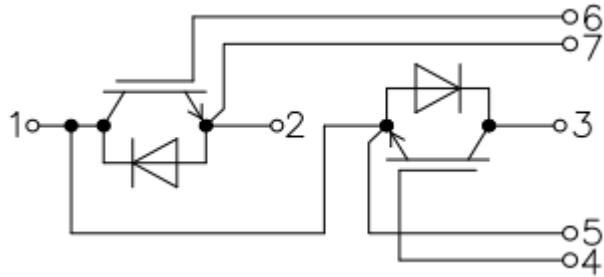


Fig 8. forward characteristic of Diode, $I_F=f(V_F)$

Internal Circuit:



Package Dimension
Dimensions in Millimeters

